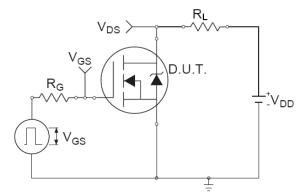

Features

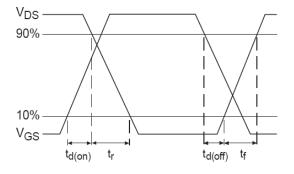
- $V_{DSS}=100V/V_{GSS}=\pm 20V/I_D=25A$ $R_{DS(ON)}=37m\Omega(max.)@V_{GS}=10V$
- Reliable and Rugged
- Advanced trench process technology
- High Density Cell Design For Low On-Resistance

Applications

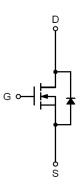
- Power Management in Inverter System
- Boost for LED Backlight

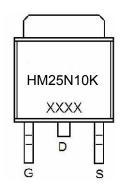
Switching Time Test Circuit and Waveforms





Pin Description





Marking and pin assignment



TO-252-2L top view

Package Marking and Ordering Information

| Device Marking | Device | Device Package | Reel Size | Tape width | Quantity |
|----------------|----------|----------------|-----------|------------|----------|
| HM25N10K | HM25N10K | TO-252-2L | | - | - |

Absolute Maximum Ratings (T_A=25°C unless otherwise noted)

| Symbol | Parameter | Typical | Unit |
|--------------|--|-----------|------|
| $ m V_{DSS}$ | Drain-Source Voltage | 100 | V |
| $ m V_{GSS}$ | Gate –Source Voltage | ±20 | V |
| I_D | T _C =100°C | 25 | A |
| | Continuous Drain Current | 16 | A |
| I_{DP} | 300us Pulsed Drain Current Tested T _C =25°C | 75 | A |
| I_{S} | Diode Continuous Forward Current | 25 | A |
| $T_{\rm J}$ | Operating Junction Temperature | 150 | °C |
| T_{STG} | Storage Temperature Range | -55 ~ 150 | °C |

Electrical Characteristics (TA=25°C unless otherwise noted)

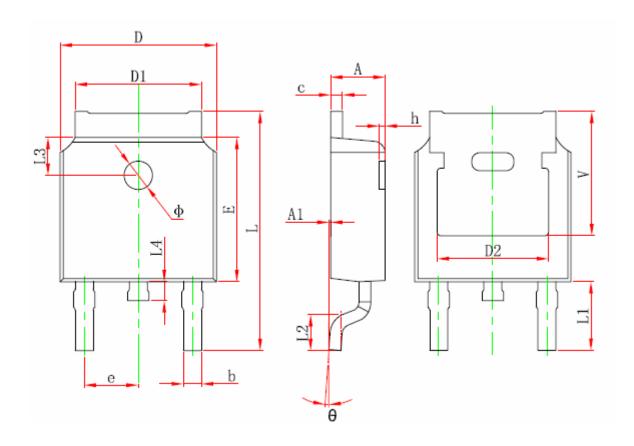
| Symbol | Parameter | Test Conditions | Min. | Тур | Max. | Unit | | |
|------------------------------|--|---|------|------|------|------|--|--|
| Static Char | acteristics | | | · | | | | |
| $\mathrm{BV}_{\mathrm{DSS}}$ | Drain-Source Breakdown Voltage | V _{GS} =0V,I _D =250uA | 100 | | | V | | |
| Ī | Zero Gate Voltage Drain Current | $V_{DS} = 80V, V_{GS} = 0V$ | | | 1 | uA | | |
| I_{DSS} | | T _J =125°C | | | 100 | uA | | |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{DS}=V_{GS},I_{D}=250uA$ | 2 | 3.3 | 4 | V | | |
| I_{GSS} | Gate Leakage Current | $V_{GS}=\pm20V, V_{DS}=0V$ | | | ±100 | nA | | |
| $R_{\mathrm{DS(on)}}^{}1}$ | Drain-Source On-Resistance | $V_{GS}=10V, I_{D}=12A$ | | 33 | 37 | mΩ | | |
| Diode Char | acteristics | | | | | | | |
| V_{SD}^{-1} | Diode Forward Voltage | $I_{SD}=12A, V_{GS}=0V$ | | | 1.1 | V | | |
| t_{rr} | Reverse Recovery Time | $I_{SD}=12A$, | | 60 | | ns | | |
| Q_{rr} | Reverse Recovery Charge | dif/dt=100A/us | | 90 | | nC | | |
| Dynamic Cl | haracteristics ² | | | | | | | |
| R_{G} | Gate Resistance | V _{GS} =0V, V _{DS} =0V, Frequency=1MHz | | 1.4 | | Ω | | |
| C_{iss} | Input Capacitance | | | 2000 | | pF | | |
| C_{oss} | Output Capacitance | V _{GS} =0V, V _{DS} =30V Frequency=1MHz | | 450 | | | | |
| C_{rss} | Reverse Transfer Capacitance | rrequency-riviriz | | 260 | | | | |
| $t_{d(on)}$ | Turn-On Delay Time | V_{DD} =50V, R_L =30 Ω | | 25 | | | | |
| $t_{\rm r}$ | Turn-On Rise Time | $I_{D}=1.0A, V_{GEN}=10V$ | | 18 | | ns | | |
| $t_{d(off)}$ | Turn-Off Delay Time | $R_G=6\Omega$ | | 60 | | - | | |
| ${ m t_f}$ | Turn-Off Fall Time | | | 78 | | | | |
| Gate Charg | Gate Charge Characteristics ² | | | | | | | |
| Q_{g} | Total Gate Charge | V _{DS} =50V, V _{GS} =10V | | 50 | | | | |
| Q_{gs} | Gate-Source Charge | $I_D=12A$ | | 13.5 | | nC | | |
| Q_{gd} | Gate-Drain Charge | 1D-12A | | 11 | | | | |

Note:

^{1:} Pulse test; pulse width ≤ 300 ns, duty cycle $\leq 2\%$.

^{2:} Guaranteed by design, not subject to production testing.

TO-252-2L Package Information



| Symbol | Dimensions | In Millimeters | Dimensions In Inches | | |
|--------|------------|----------------|----------------------|-------|--|
| | Min. | Max. | Min. | Max. | |
| Α | 2.200 | 2.400 | 0.087 | 0.094 | |
| A1 | 0.000 | 0.127 | 0.000 | 0.005 | |
| b | 0.660 | 0.860 | 0.026 | 0.034 | |
| С | 0.460 | 0.580 | 0.018 | 0.023 | |
| D | 6.500 | 6.700 | 0.256 | 0.264 | |
| D1 | 5.100 | 5.460 | 0.201 | 0.215 | |
| D2 | 4.830 | REF. | 0.190 REF. | | |
| E | 6.000 | 6.200 | 0.236 | 0.244 | |
| е | 2.186 | 2.386 | 0.086 | 0.094 | |
| L | 9.800 | 10.400 | 0.386 | 0.409 | |
| L1 | 2.900 REF. | | 0.114 REF. | | |
| L2 | 1.400 | 1.700 | 0.055 | 0.067 | |
| L3 | 1.600 REF. | | 0.063 REF. | | |
| L4 | 0.600 | 1.000 | 0.024 | 0.039 | |
| Ф | 1.100 | 1.300 | 0.043 | 0.051 | |
| θ | 0° | 8° | 0° | 8° | |
| h | 0.000 | 0.300 | 0.000 | 0.012 | |
| V | 5.350 REF. | | 0.211 REF. | | |



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